

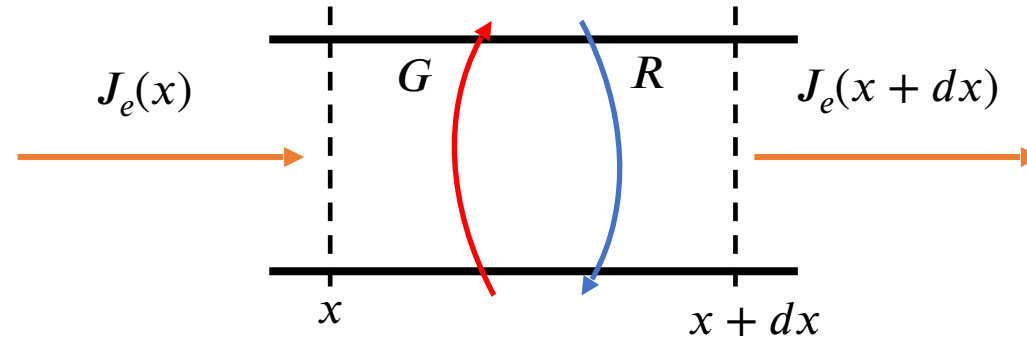
**Current Flow: Motion of electron and hole**

**Generation: Local creation of electron-hole pairs**

**Recombination: Local annihilation of electron-hole pairs**

**Non-equilibrium Condition**

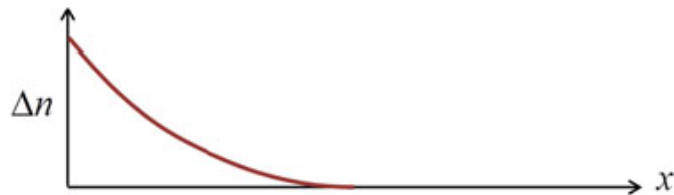
The combined effect of all types of carrier action within a semiconductor, drift, diffusion, and recombination-generation is described by the following continuity equation.



$$\frac{dn}{dt} A dx = \left( \frac{J_{e(total)}(x)}{-e} - \frac{J_{e(total)}(x + dx)}{-e} \right) A + (G_e - R_e) A dx$$

$G_e$  is the generation rate

$R_e$  is the recombination rate



- For the sake of simplicity, assume that all light is absorbed at the surface: electron generation at the surface only. ( $G_{opt}, x > 0$ ) = 0
- No electric field:  $J_{e(drift)} = 0$

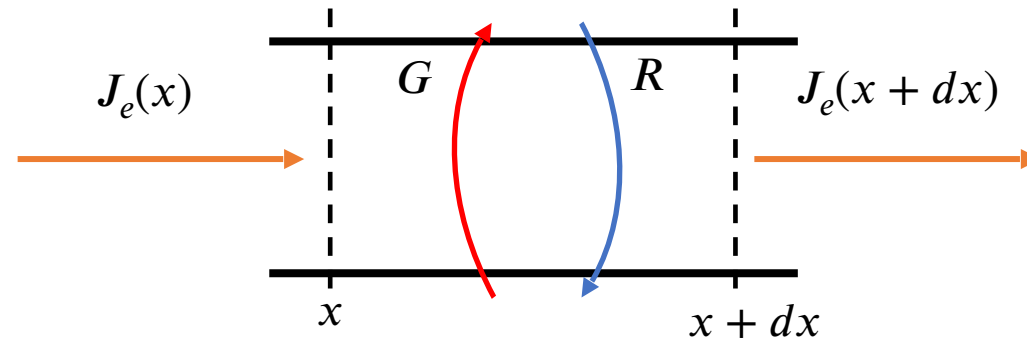
$$\Delta n(x) = \Delta n(0) \exp\left(-\frac{x}{\sqrt{D_e \tau_e}}\right) = \Delta n(0) \exp\left(-\frac{x}{L_e}\right)$$

$\tau_e$  = carrier lifetime

$L_e = \sqrt{D_e \tau_e}$  (diffusion length)



The combined effect of all types of carrier action within a semiconductor, drift, diffusion, and recombination-generation is described by the following continuity equation.

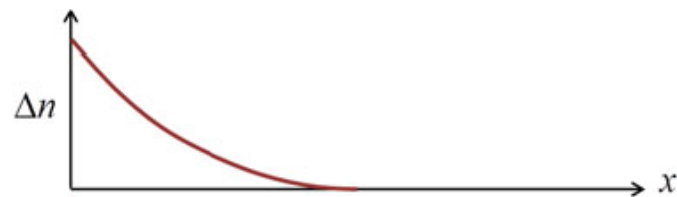


- The excess electron density decreases exponentially as the distance from the light illuminated front surface increases and the carrier diffusion length decreases.

- No electric field:  $J_{e(drift)} = 0$

$$\Delta n(x) = \Delta n(0) \exp\left(-\frac{x}{\sqrt{D_e \tau_e}}\right) = \Delta n(0) \exp\left(-\frac{x}{L_e}\right)$$

$$L_e = \sqrt{D_e \tau_e} \text{ (diffusion length)}$$



Under non-equilibrium conditions, an excess or deficiency of charge carriers exists in a semiconductor (under illumination).

- An increase in the densities of the excess carriers is accompanied by a shift of the quasi-Fermi levels.
- As the electron density increases, the quasi-Fermi level of the electron steadily approaches the CB.
- In contrast, the quasi-Fermi level of the hole approaches the VB for increasing hole densities.
- In this way, the quasi-Fermi levels of electron and hole shift in opposite directions, and their energy difference becomes larger as the carrier densities increase.

$$n = n_0 + \Delta n$$

$$p = p_0 + \Delta p$$

$n$  and  $p$ : The electron and the hole density under non-equilibrium.

$n_0$  and  $p_0$ : The electron and the hole density under equilibrium.

$$n = N_C \exp\left[\frac{(E_{Fn} - E_C)}{k_B T}\right] = n_i \exp\left[\frac{(E_{Fn} - E_i)}{k_B T}\right]$$

$$p = N_V \exp\left[\frac{(E_V - E_{Fp})}{k_B T}\right] = n_i \exp\left[\frac{(E_i - E_{Fp})}{k_B T}\right]$$

$E_{Fn}$ : The quasi-Fermi energy for electrons.

$E_{Fp}$ : The quasi-Fermi energy for holes.

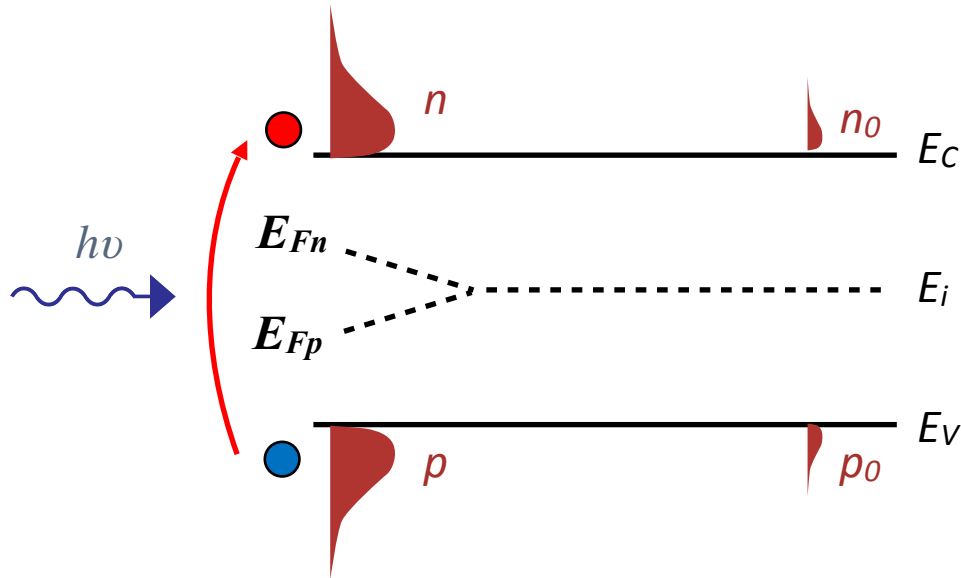


$$E_{Fn} = E_i + k_B T \ln\left(\frac{n}{n_i}\right)$$

$$E_{Fp} = E_i - k_B T \ln\left(\frac{p}{n_i}\right)$$

# Non-equilibrium Carrier Concentration

Under non-equilibrium conditions, an excess or deficiency of charge carriers exists in a semiconductor (under illumination).



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$$E_{Fn} = E_i + k_B T \ln\left(\frac{n}{n_i}\right)$$

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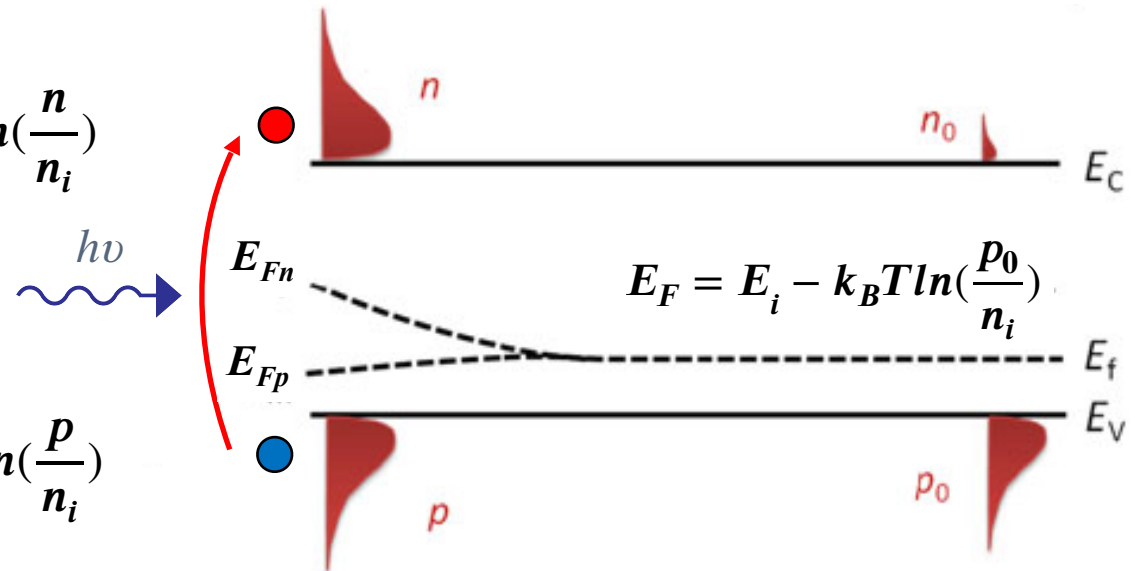
- In case of a **p-type SC**,  $p_0 \gg n_0$ .
- The excess electrons form the electron quasi-Fermi level.
- The contribution of the excess carriers to the total carrier density is **smaller for the holes**.
- The shift in the hole quasi-Fermi level is also smaller.

$$n = n_0 + \Delta n \approx \Delta n$$

$$E_{Fn} = E_i + k_B T \ln\left(\frac{n}{n_i}\right)$$

$$p = p_0 + \Delta p \approx p_0$$

$$E_{Fp} = E_i - k_B T \ln\left(\frac{p}{n_i}\right)$$



# EPFL Non-equilibrium Carrier Concentration

Example) A piece of Si doped with  $10^{16} \text{ cm}^{-3}$  shallow donors is illuminated with light generating  $10^{15} \text{ cm}^{-3}$  excess electrons and holes. Calculate the quasi-Fermi energies relative to the intrinsic energy and compare it to the Fermi energy in the absence of illumination.

Solution)  $n = n_0 + \Delta n = 10^{16} + 10^{15} = 1.1 \times 10^{16} \text{ cm}^{-3}$

$$p = p_0 + \Delta p = 10^{15} \text{ cm}^{-3}$$

**the number of minority carriers in an illuminated solar cell can be approximated by the number of light generated carriers**

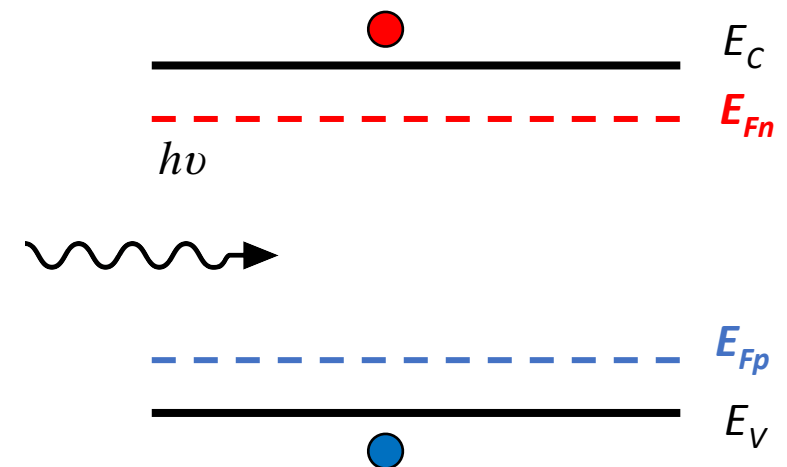
The quasi-Fermi levels under illumination:

$$E_{Fn} - E_i = k_B T \ln\left(\frac{n}{n_i}\right) = 0.0259 \times \ln\left(\frac{1.1 \times 10^{16}}{10^{10}}\right) = 360 \text{ meV}$$

$$E_i - E_{Fp} = k_B T \ln\left(\frac{p}{n_i}\right) = 0.0259 \times \ln\left(\frac{1 \times 10^{15}}{10^{10}}\right) = 298 \text{ meV}$$

The Fermi levels in absence of light:

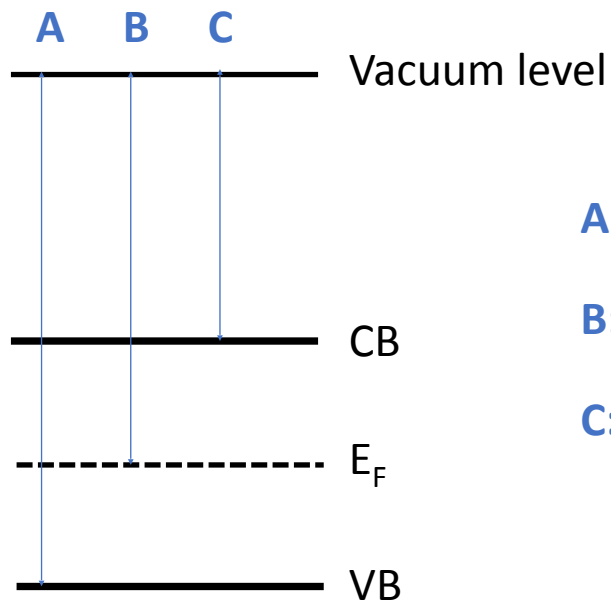
$$E_F - E_i = k_B T \ln\left(\frac{n}{n_i}\right) = 0.0259 \times \ln\left(\frac{1 \times 10^{16}}{10^{10}}\right) = 358 \text{ meV}$$



Work function (WF)

Ionization energy (IE)

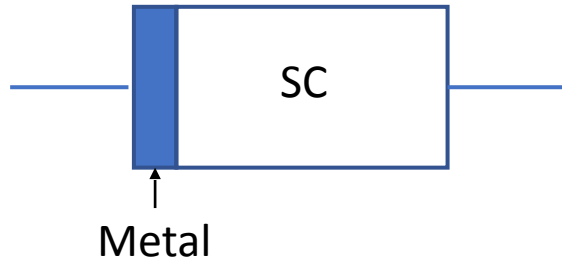
Electron affinity (EA)

**A: Ionization energy (IE)****B: Work function (WF)****C: Electron affinity (EA)**

**Ionization Energy** is the energy required to remove the outermost electron in an atom or molecule in its ground state to infinity, i.e. cause the atom to become ionized.

**Work Function ( $\phi$ )** is the amount of energy required to transfer an electron from the  $E_F$  to the vacuum level.

**Electron affinity ( $\chi$ )** is defined as the potential energy change of an atom or molecule when an electron is added to a neutral gaseous atom to form a negative ion.



Metal-SC (M-S) junctions can behave as either Schottky barriers or as Ohmic contacts, depending on the interface properties.

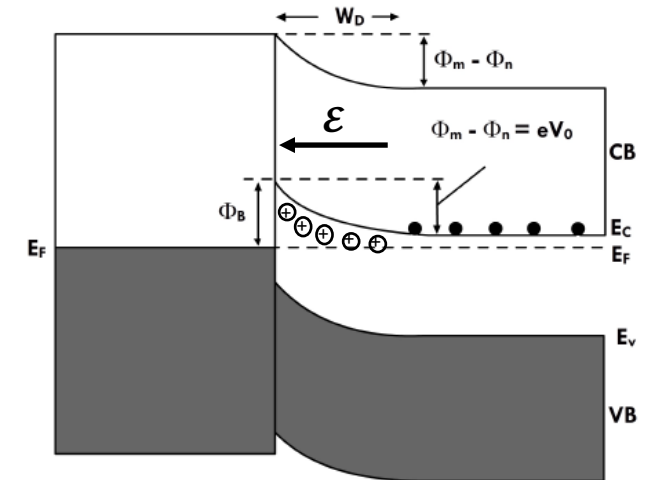
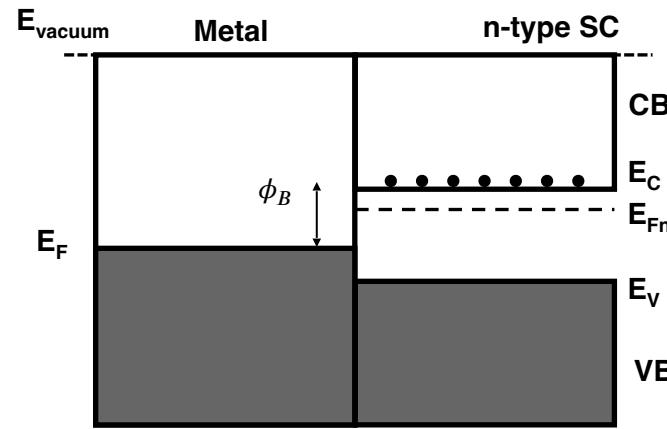
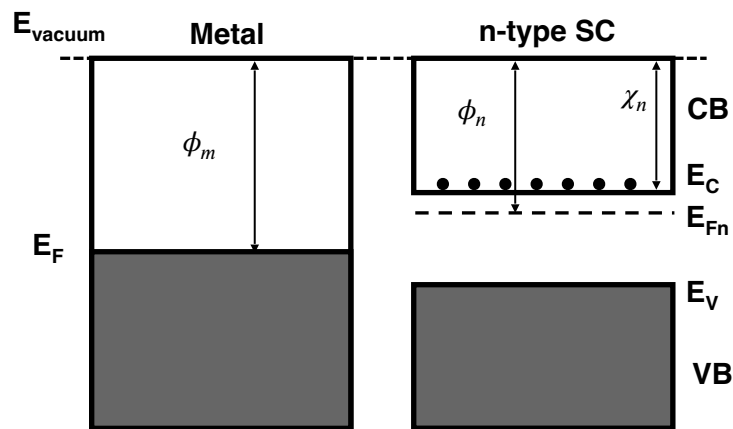
Schottky junction:  $\phi_m > \phi_{sc}$

Ohmic junction:  $\phi_m < \phi_{sc}$

Before contact

After contact

In thermal equilibrium



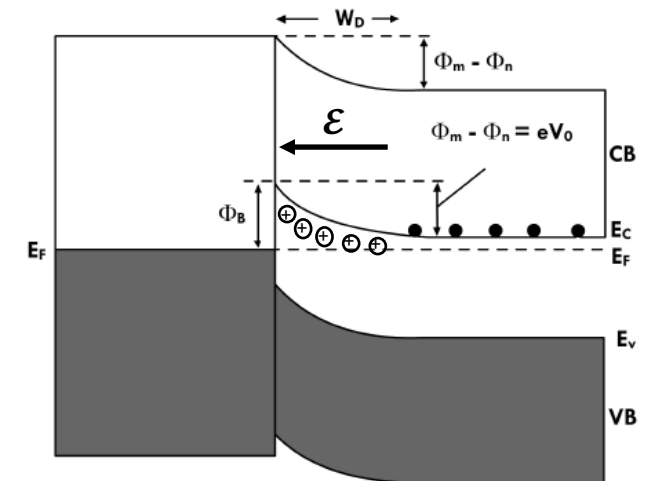
Ionization E, Electron Affinity etc: <https://pubs.rsc.org/en/content/articlehtml/2016/mh/c5mh00160a>

$W_d$ : Depletion width

# EPFL Metal-Semiconductor Junction

- The barrier height,  $\Phi_B$ , is defined as the potential an electron overcome to cross the junction.
- A built in potential in the Schottky junction,  $V_0$  is a constant potential difference across the junction at equilibrium = difference between the work functions of materials at equilibrium.
- When a Schottky junction is formed between the metal and semiconductor, a **positive potential is formed on the SC side. Because the depletion region extends within a certain depth in the SC, there is bending of the energy bands on the SC side.**
- Bands bend up in the direction of the electric field (field goes from positive charge to negative charge): the energy bands bend up going from n-type SC to metal
- There is a certain region in the SC (denoted by  $W$ ) where the bands bend (this is the depletion region). Another name for the **depletion region** is the **space charge layer**.

In thermal equilibrium



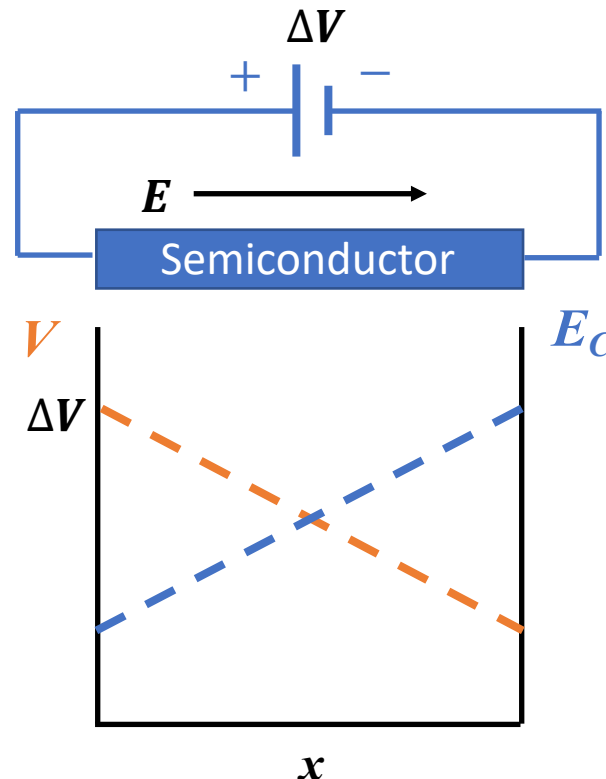
$W_d$ : Depletion width

# EPFL Electric Potential vs Electric Field

- The electric field ( $E$ ) is related to the electric potential by  $E(x) = -\frac{dV}{dx}$
- The difference in potential energy between 2 points in an E-field containing a charge  $Q$ :  $\Delta PE = Q \cdot E \cdot \Delta x$

$$E(x) = -\frac{dV}{dx} = \frac{1}{Q} \frac{dPE}{dx} \quad PE \text{ is } E_C \text{ or } E_V!$$

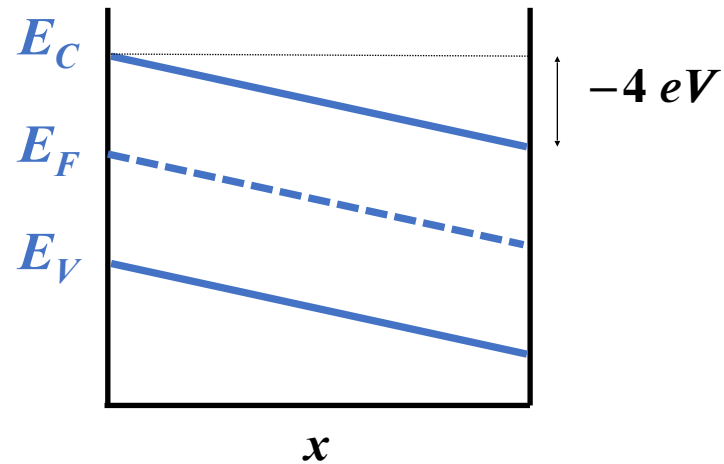
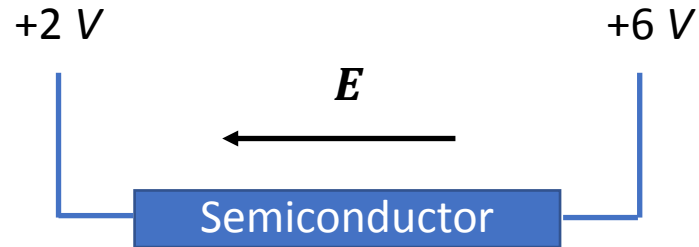
- High electric potential ( $V$ ) correlates with a high concentration of positive charge.



More positive voltage lowers  $E_C$  and  $E_V$ .

More negative voltage raises  $E_C$  and  $E_V$ .

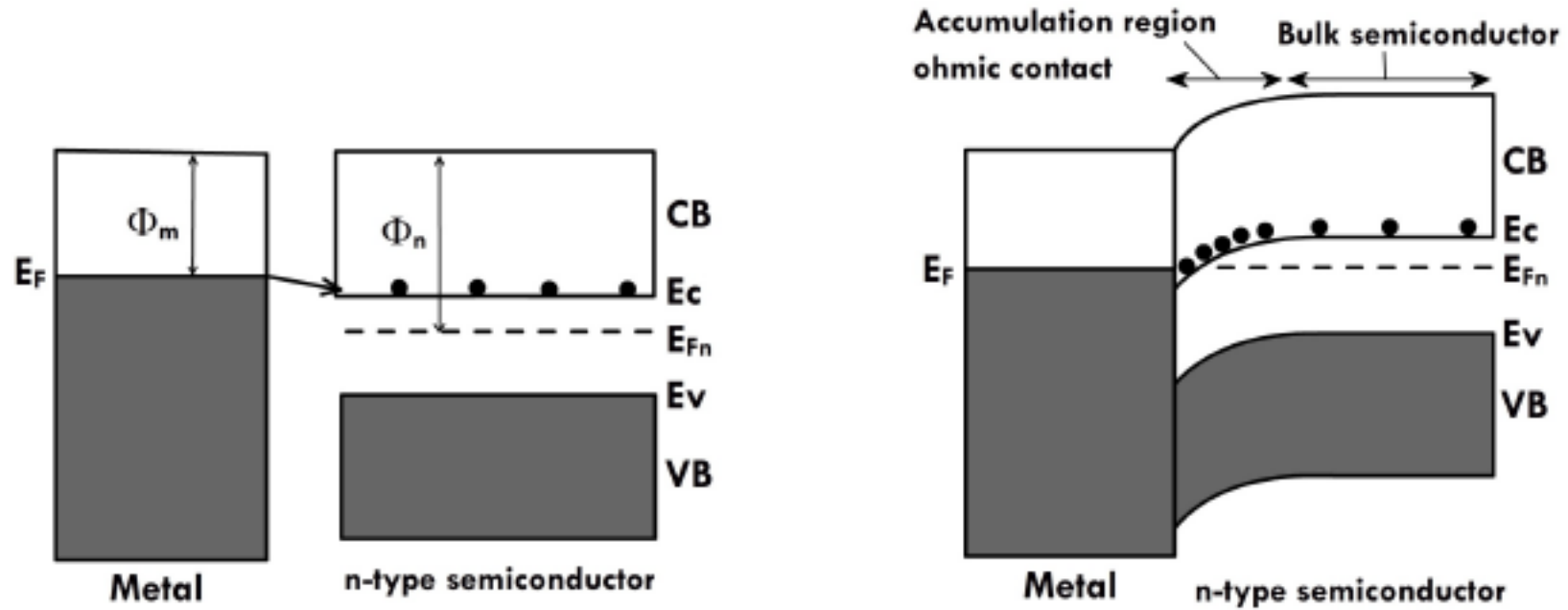
Example)



$$E(x) = -\frac{dV}{dx} = \frac{1}{Q} \frac{dPE}{dx}$$

$$\Delta PE = Q \cdot \Delta V = -e \cdot (4V) = -4 eV$$

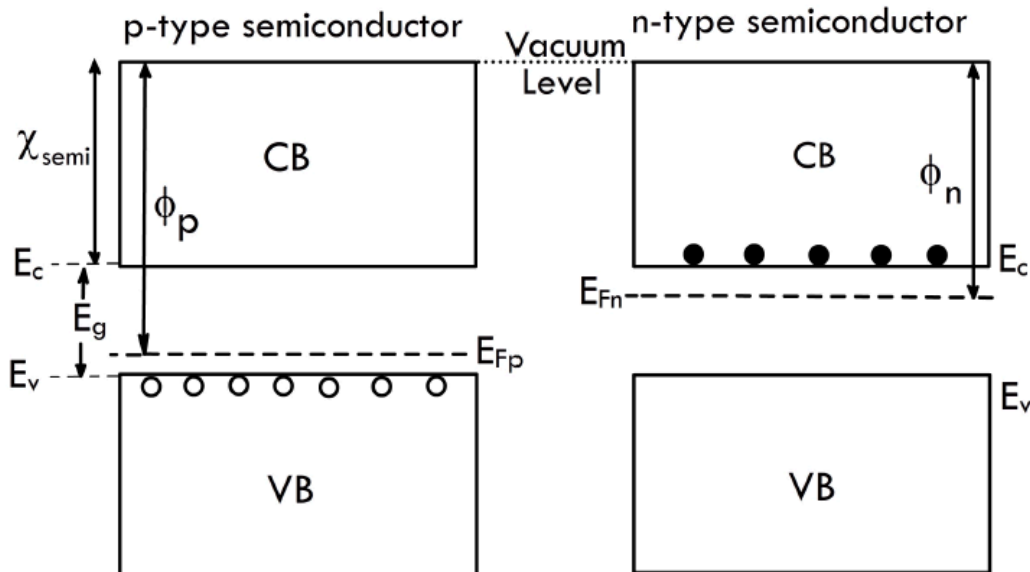
- The Fermi level is also slanted with  $E_C$  and  $E_V$  because there is current flow.
- The slant is opposite for a hole but the energy diagram shows in general electron energy.



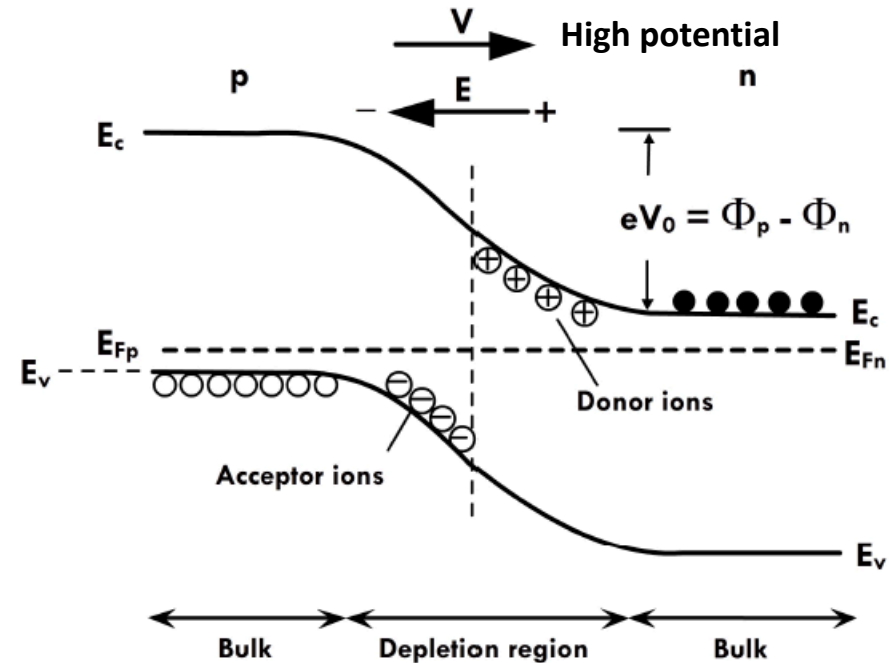
# EPFL pn Junction (Homojunction or Heterojunction)

- In thermal equilibrium after contact, the Fermi levels line up at equilibrium.
- There are excess electrons on the n-side and excess holes on the p-side.
- The electrons move from the n side to the p side and combine with the holes, while holes move from p to n side and combine with the electrons.
- Because of the movement of majority carriers a net positive charge develops on the n-side (due to the positively charged donor ions) and a negative charge develops on the p-side (due to negatively charged acceptor ions).
- Thus, an E-field is formed going from the n-side to the p-side and there is a built-in potential, from the p to the n side.

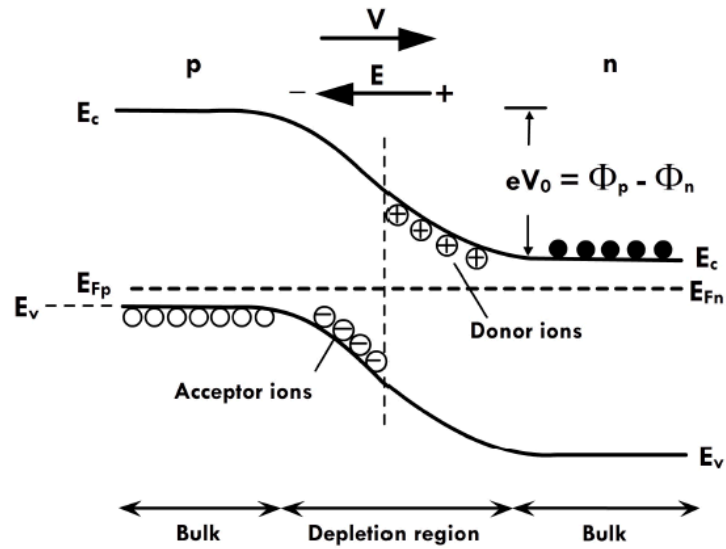
Before contact



In thermal equilibrium



# Depletion Region in pn Junction



The total depletion region width:  $w_0 = w_p + w_n$

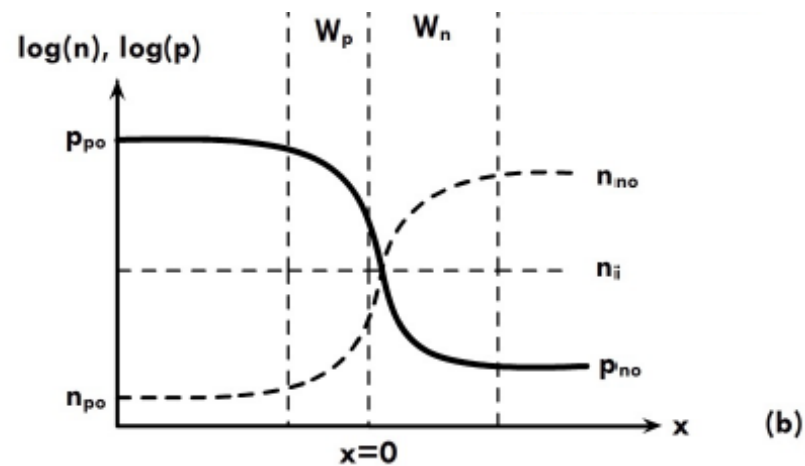
Charge balance in the region:  $N_A A w_p = N_D A w_n$

The ratio of the depletion widths:

$$\frac{w_p}{w_n} = \frac{N_D}{N_A}$$

$w_p < w_n$  if  $N_A > N_D$

$w_p \ll w_n$  if  $N_A \gg N_D$  p<sup>+</sup>n junction



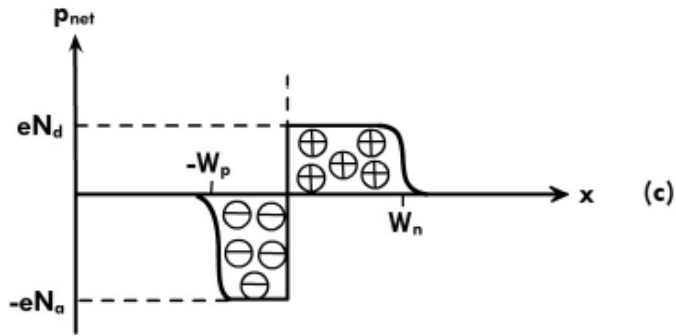
Carrier concentrations in the p side:  $p_{p0} = N_A$

$$n_{p0} = \frac{n_i^2}{N_A}$$

Carrier concentrations in the n side:  $n_{n0} = N_D$

$$p_{n0} = \frac{n_i^2}{N_D}$$

# EPFL Depletion Region in pn Junction



The charge density in the depletion region = abrupt charge distribution:

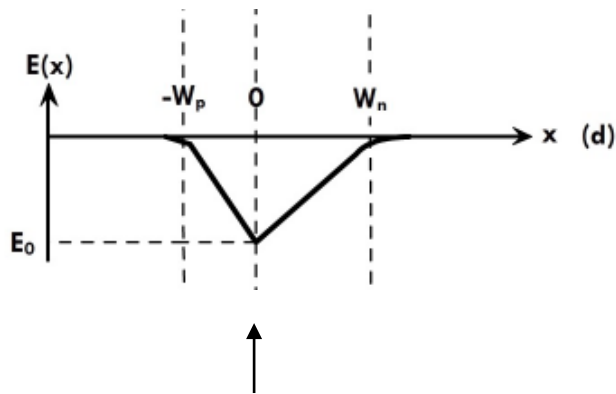
$$\rho_{net} = -eN_A \quad \text{for } -w_p < x < 0$$

$$\rho_{net} = eN_D \quad \text{for } 0 < x < w_n$$

For 1 dimensional interface by Gauss law:  $\frac{dE}{dx} = \frac{\rho_{net}}{\epsilon}$

The field obtained by integrating the total charge density:

$$E(x) = \frac{1}{\epsilon} \int \rho_{net}(x) dx$$



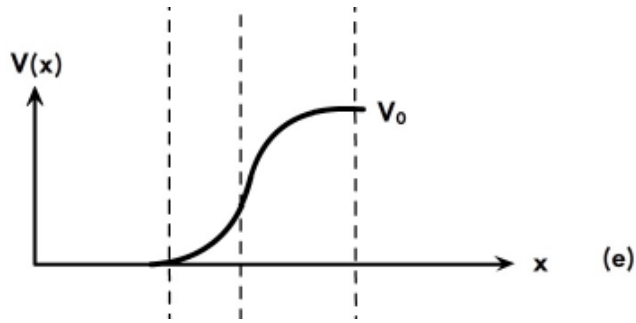
At  $x = 0$  the E-field must match:

$$E(0) = -\frac{eN_A w_p}{\epsilon} = -\frac{eN_D w_n}{\epsilon}$$

With the boundary condition that the field must go to zero at the boundaries i.e.  $x = -w_p$  and  $x = w_n$ :

$$E(x) = -\frac{eN_A}{\epsilon} (x + w_p) \quad \text{for } -w_p < x < 0$$

$$E(x) = \frac{eN_D}{\epsilon} (x - w_n) \quad \text{for } 0 < x < w_n$$



The electric field is related to the potential by  $E(x) = -\frac{dV}{dx}$

With the boundary conditions are set such that  $V = 0$  at  $x = -w_p$  and  $V = V_0$  at  $x = w_n$ , where  $V_0$  is the total potential i.e. built-in potential:

$$V(x) = \frac{eN_A}{2\varepsilon}(x + w_p)^2 \quad \text{for } -w_p < x < 0$$

$$V(x) = V_0 - \frac{eN_D}{2\varepsilon}(x - w_n)^2 \quad \text{for } 0 < x < w_n$$

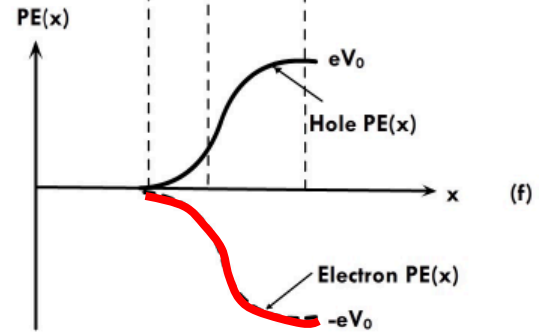
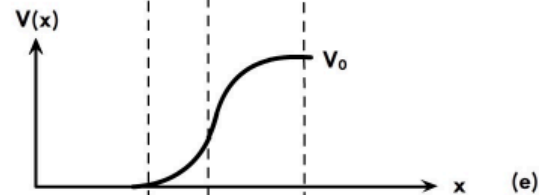
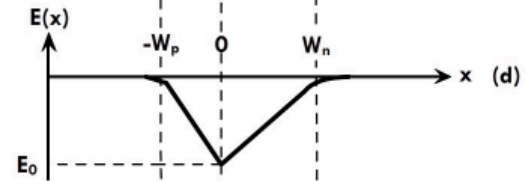
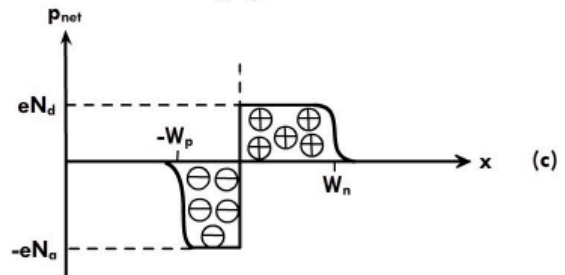
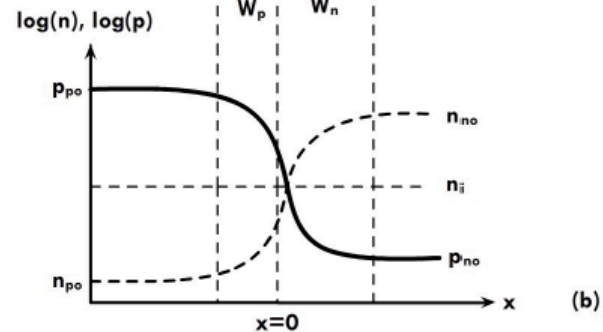
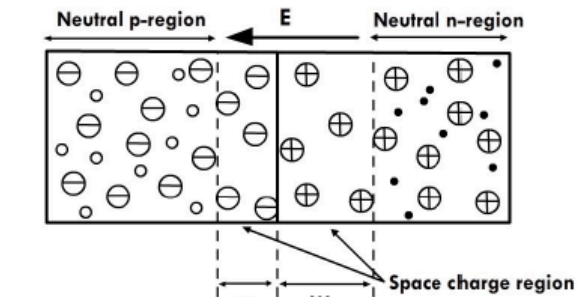
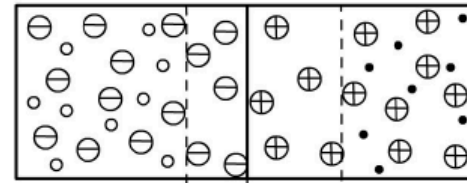
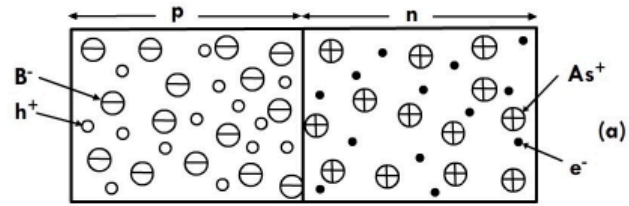
The potential function should be continuous and  $V$  should be equal at  $x = 0$ :  $\frac{eN_A}{2\varepsilon}w_p^2 = V_0 - \frac{eN_D}{2\varepsilon}w_n^2$

Rearrangement and using  $\frac{w_p}{w_n} = \frac{N_D}{N_A}$  and  $w_0 = w_p + w_n$ :  $w_0 = \sqrt{\frac{2\varepsilon V_0}{e} \left( \frac{N_A + N_D}{N_A N_D} \right)}$

Th built-in potential:  $V_0 = E_{Fn} - E_{Fp} = k_B T \ln \left( \frac{np}{n_i^2} \right)$

from  $E_{Fn} - E_i = k_B T \ln \left( \frac{n}{n_i} \right)$  and  $E_i - E_{Fp} = k_B T \ln \left( \frac{p}{n_i} \right)$

# Depletion Region in pn Junction



- (a) Schematic of the pn junction
- (b) Carrier concentration across the junction
- (c) Charge density variation
- (d) Electric field
- (e) Potential
- (f) Potential energy in the depletion region

# EPFL Depletion Region in pn Junction

Example) An abrupt silicon p-n junction consists of a p-type region containing  $5 \times 10^{16} \text{ cm}^{-3}$  acceptors and an n-type region containing  $10^{17} \text{ cm}^{-3}$  donors.

- Calculate the thermal equilibrium density of electrons and holes in the p-type region as well as both densities in the n-type region.
- Calculate the built-in potential of the p-n junction.
- Calculate the built-in potential of the p-n junction at 400 K.

Solution) a. In the p-type region:  $p = N_A = 5 \times 10^{16} \text{ cm}^{-3}$        $n = \frac{n_i^2}{p} = \frac{10^{20}}{5 \times 10^{16}} = 2 \times 10^3 \text{ cm}^{-3}$

In the n-type region:  $n = N_D = 10^{17} \text{ cm}^{-3}$        $p = \frac{n_i^2}{n} = \frac{10^{20}}{10^{17}} = 1 \times 10^3 \text{ cm}^{-3}$

b. The built-in potential:  $E_{Fn} - E_i = k_B T \ln\left(\frac{n}{n_i}\right)$        $E_i - E_{Fp} = k_B T \ln\left(\frac{p}{n_i}\right)$

$$E_{Fn} - E_{Fp} = k_B T \ln\left(\frac{np}{n_i^2}\right) = 0.0259 \times \ln\left(\frac{10^{17} \times 5 \times 10^{16}}{10^{20}}\right) = 0.817 \text{ V}$$

c. The built-in potential at 400 K:

$$E_{Fn} - E_{Fp} = k_B T \ln\left(\frac{np}{n_i^2}\right) = 0.0345 \times \ln\left(\frac{10^{17} \times 5 \times 10^{16}}{(4.52 \times 10^{12})^2}\right) = 0.500 \text{ V}$$



Example ) An abrupt silicon ( $n_i = 10^{10} \text{ cm}^{-3}$ ) p-n junction consists of a p-type region containing  $5 \times 10^{16} \text{ cm}^{-3}$  acceptors and an n-type region containing  $10^{17} \text{ cm}^{-3}$  donors.

- Calculate the total width of the depletion region if the applied voltage equals 0, 0.5 and -2.5 V.
- Calculate the potential across the depletion region in the n-type semiconductor at 0, 0.5 and -2.5 V.
- Calculate maximum electric field in the depletion region at 0, 0.5 and -2.5 V.

Solution) The built-in potential of this p-n junction was calculated and the value was 0.814 V.

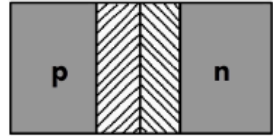
a. Calculate the total width of the depletion region: 
$$w_0 = \sqrt{\frac{2\epsilon(V_0 - V_{ext})}{e} \left( \frac{N_A + N_D}{N_A N_D} \right)}$$

b. Calculate the potential across the depletion region in the n-type semiconductor: 
$$\frac{eN_D}{2\epsilon} w_n^2, \quad w_n = \frac{w_0}{1 + \frac{N_D}{N_A}}$$

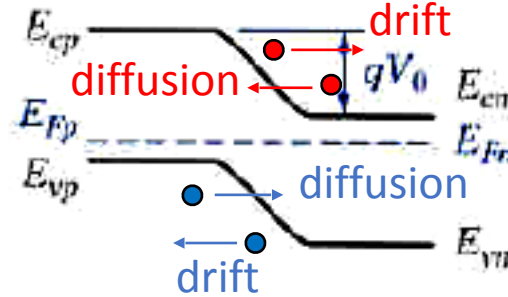
c. Calculate maximum electric field in the depletion region: 
$$E(0) = -\frac{eN_D w_n}{\epsilon}$$

	$V_{ext} = 0 \text{ V}$	$V_{ext} = 0.5 \text{ V}$	$V_{ext} = -2.5 \text{ V}$
$w_0 (\mu\text{m})$	0.178	0.111	0.358
$V_n (\text{V})$	0.272	0.106	1.106
$E(0) (\text{kV/cm})$	91.9	57.2	185

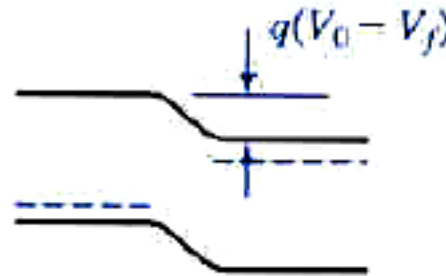
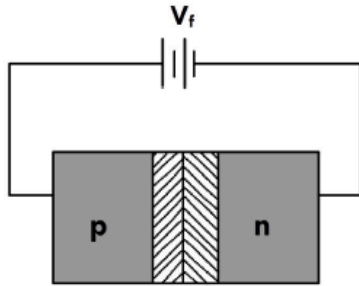
**Equilibrium**



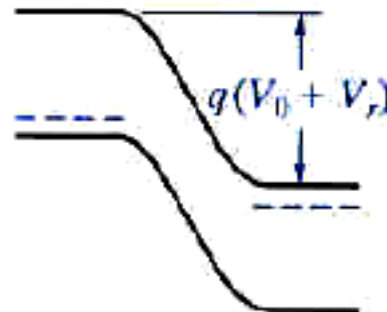
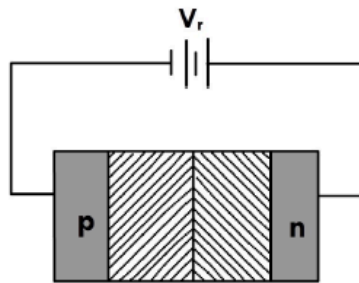
**Energy band**



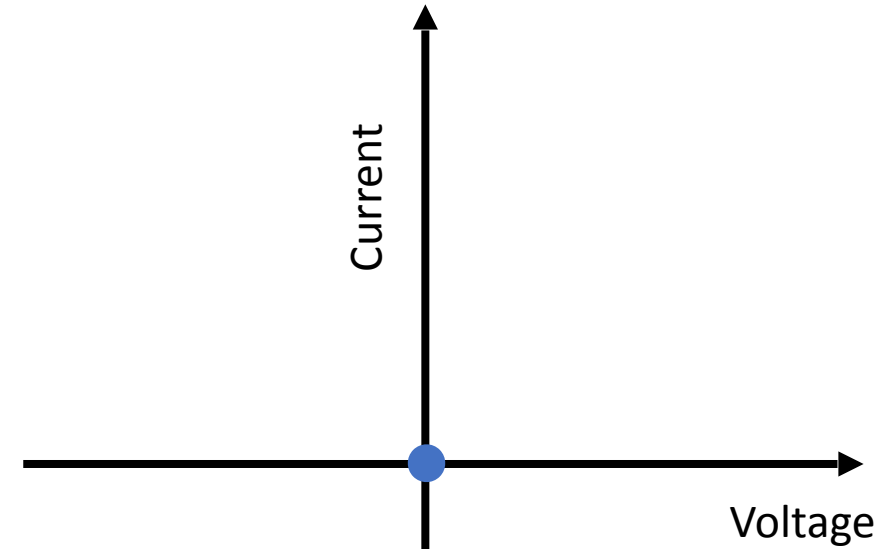
**Forward bias**



**Reverse bias**



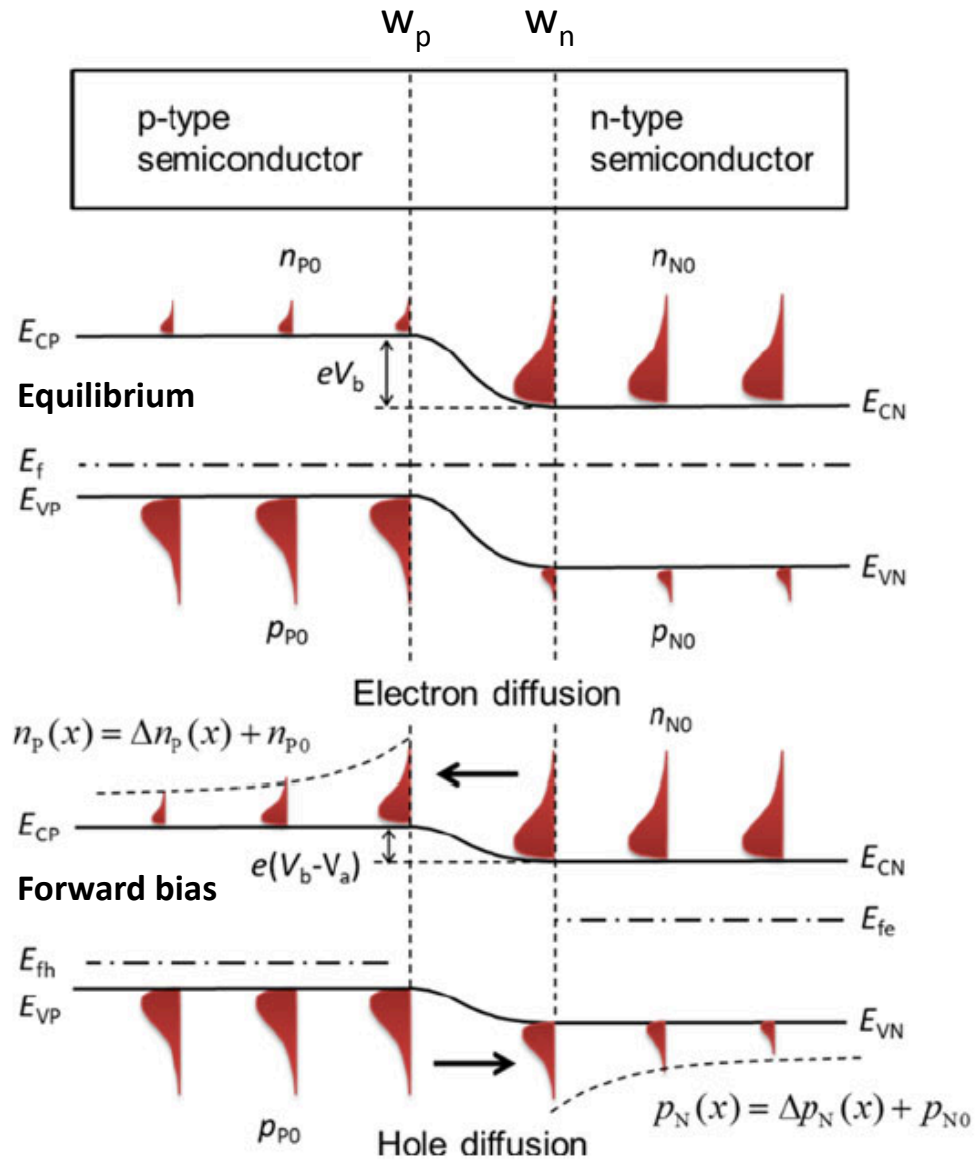
**Equilibrium**



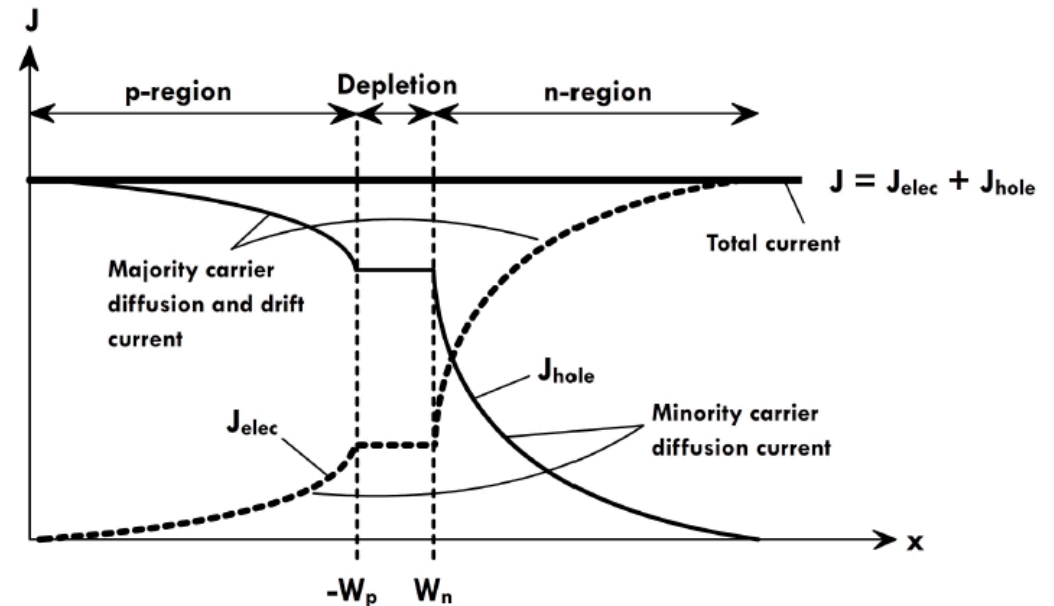




# IV Characteristics of a pn Junction (Forward Bias)

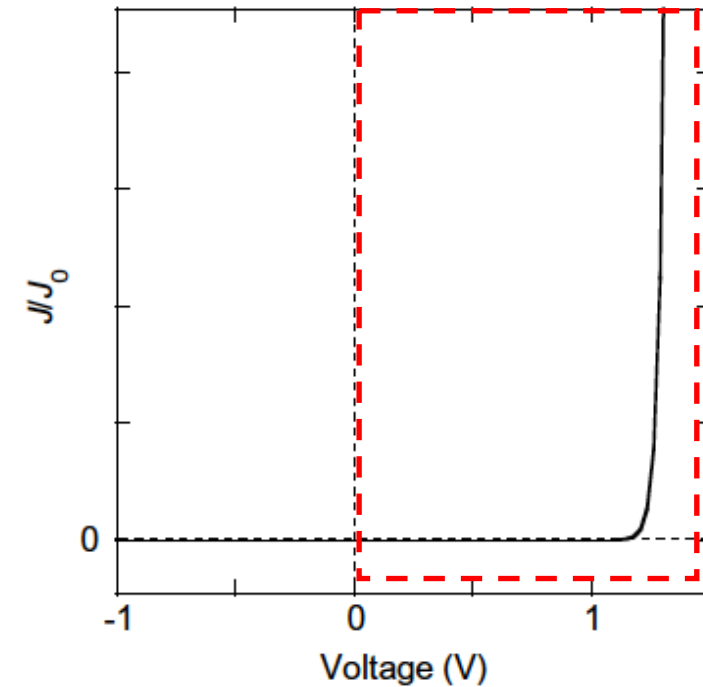


- Under forward bias, the potential barrier at the junction interface is lowered.
- The electrons flow from the n-type region into the p-type region while holes flow in the reverse direction.
- The total current is a constant independent of position.
- The dominant carrier transport in a p–n junction is diffusion and the drift current of the minority carriers is not considered.



$$\begin{aligned} J_{total} &= J_{e(diff)}(w_P) + J_{h(diff)}(w_N) \\ &= e \left( \frac{D_e n_{P0}}{L_e} + \frac{D_h p_{N0}}{L_h} \right) \left\{ \exp\left(\frac{eV_a}{k_B T}\right) - 1 \right\} \\ &= J_0 \left\{ \exp\left(\frac{eV_a}{k_B T}\right) - 1 \right\} \end{aligned}$$

The Shockley diode equation

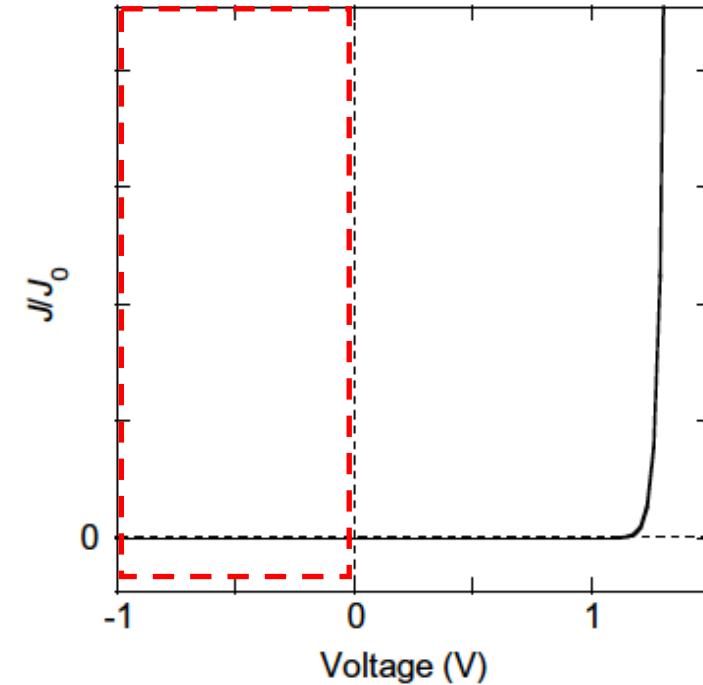


$$\begin{aligned}
 J_{total} &= J_{e(diff)}(w_P) + J_{h(diff)}(w_N) \\
 &= e \left( \frac{D_e n_{P0}}{L_e} + \frac{D_h p_{N0}}{L_h} \right) \left\{ \exp\left(\frac{eV_a}{k_B T}\right) - 1 \right\} \\
 &= J_0 \left\{ \exp\left(\frac{eV_a}{k_B T}\right) - 1 \right\}
 \end{aligned}$$

The Shockley diode equation

$$\begin{aligned}
 J_0 &= e \left( \frac{D_e n_{P0}}{L_e} + \frac{D_h p_{N0}}{L_h} \right) = en_i^2 \left( \sqrt{\frac{D_e}{\tau_e}} \frac{1}{N_A} + \sqrt{\frac{D_h}{\tau_h}} \frac{1}{N_D} \right) \\
 &= e \left( \sqrt{\frac{D_e}{\tau_e}} \frac{1}{N_A} + \sqrt{\frac{D_h}{\tau_h}} \frac{1}{N_D} \right) N_C N_V \exp\left(-\frac{E_g}{k_B T}\right)
 \end{aligned}$$

The saturation current



- The reverse bias causes the potential barrier increases and **the carrier transport across the junction will be inhibited.**
- Under ideal condition, a constant value of  $J_0$  is maintained for wide range of reverse bias voltages.
- If an excessively high reverse bias is applied, a tunnel current flow at the depletion layer leads to a significant increase of the reverse current (at breakdown voltage).

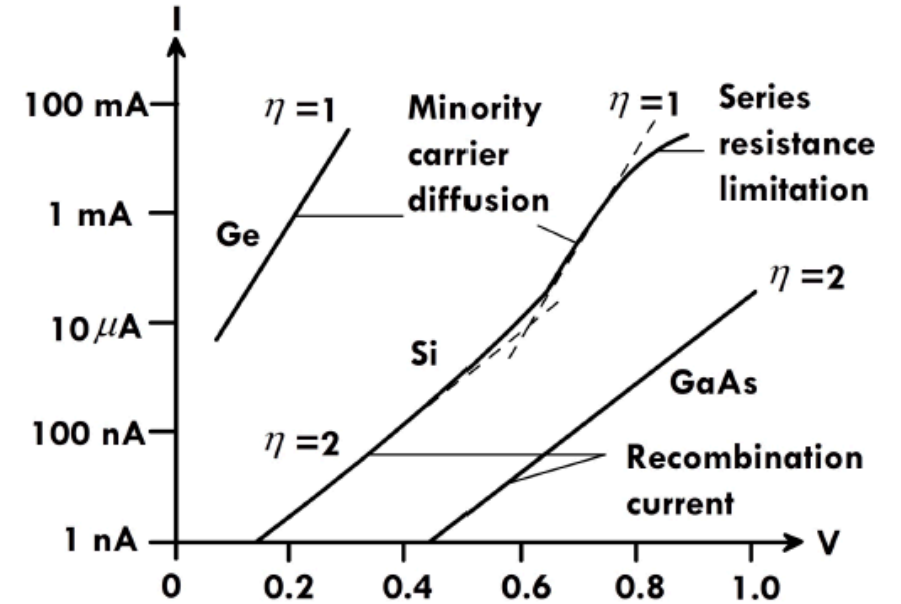
For actual diodes, the equation becomes:

$$J_{total} = J_0 \left\{ \exp\left(\frac{eV_a}{nk_B T}\right) - 1 \right\}$$

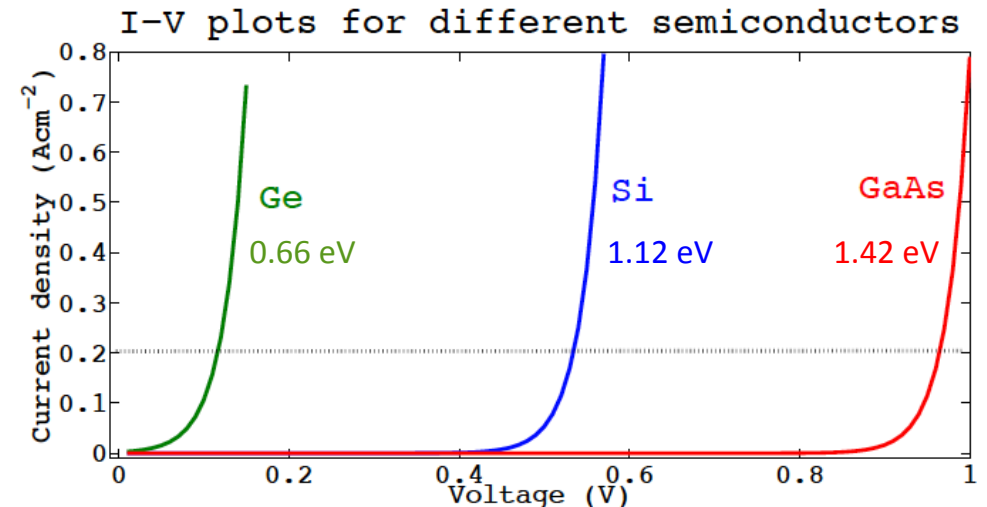
$n$  = ideality factor, a number between 1 and 2.

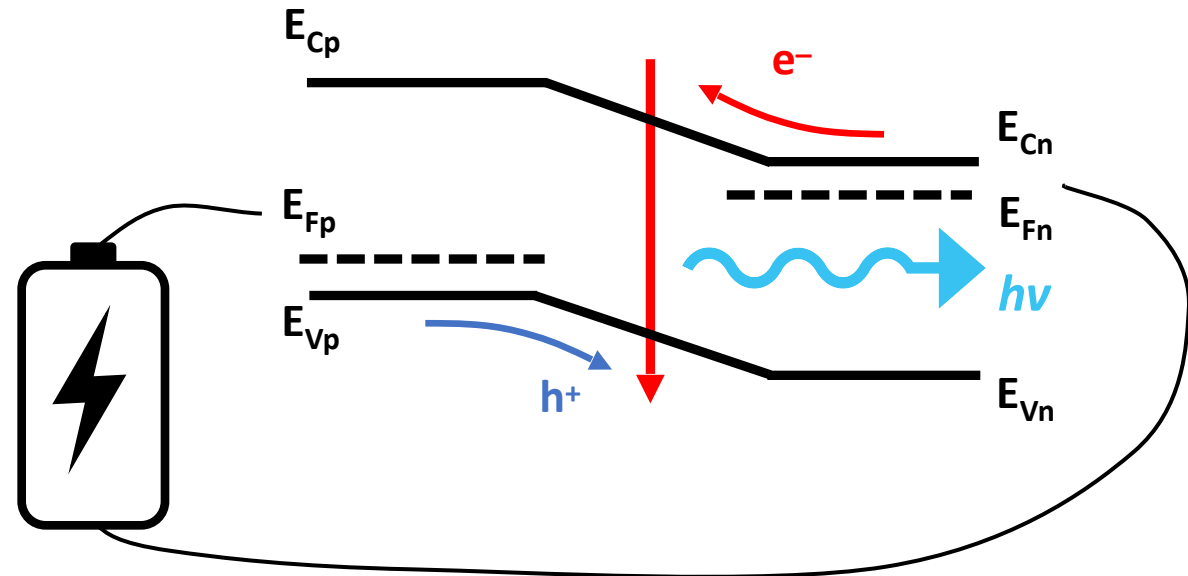
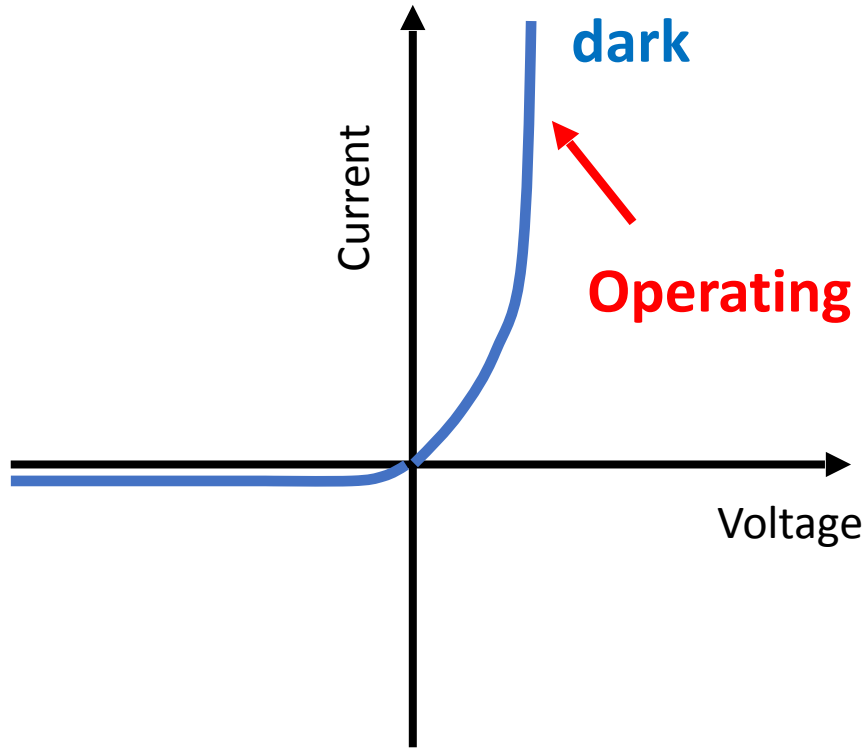
The  $n$  is close to 1 for the case of an “ideal” like diode and when  $n$  shifts to 2, it account for imperfect junctions (mainly due to recombination).

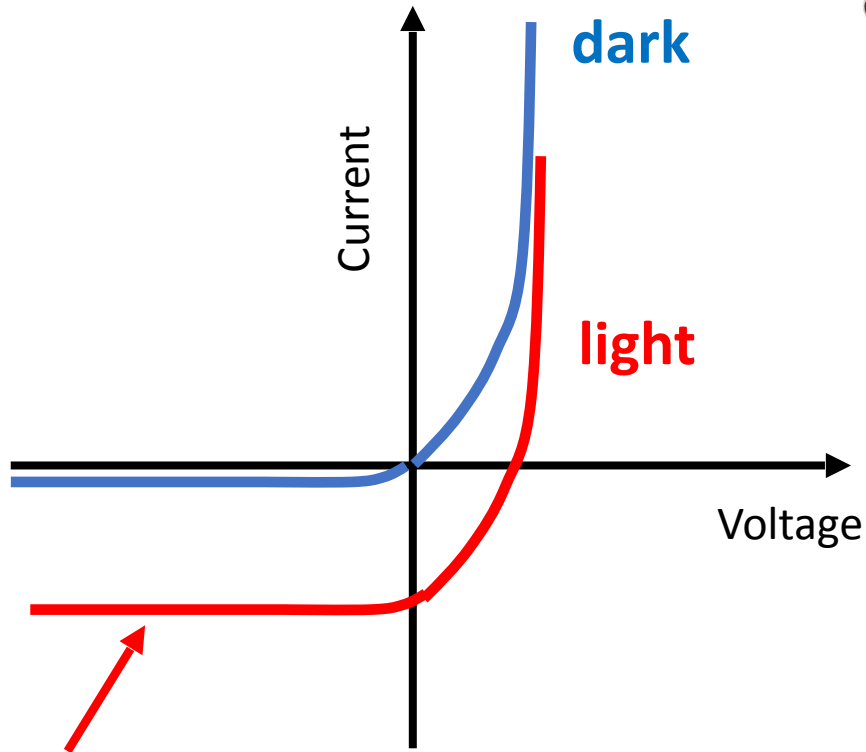
$$\begin{aligned}
 J_{total} &= e \left( \sqrt{\frac{D_e}{\tau_e} \frac{1}{N_A}} + \sqrt{\frac{D_h}{\tau_h} \frac{1}{N_D}} \right) N_C N_V \exp\left(-\frac{E_g}{k_B T}\right) \left\{ \exp\left(\frac{eV_a}{k_B T}\right) - 1 \right\} \\
 &\approx e \left( \sqrt{\frac{D_e}{\tau_e} \frac{1}{N_A}} + \sqrt{\frac{D_h}{\tau_h} \frac{1}{N_D}} \right) N_C N_V \exp\left(-\frac{E_g}{k_B T}\right) \exp\left(\frac{eV_a}{k_B T}\right) \\
 &= e \left( \sqrt{\frac{D_e}{\tau_e} \frac{1}{N_A}} + \sqrt{\frac{D_h}{\tau_h} \frac{1}{N_D}} \right) N_C N_V \exp\left(\frac{eV_a - E_g}{k_B T}\right)
 \end{aligned}$$



Adapted from Principles of Electronic Materials - S.O. Kasap.







**Operation voltage to increase E-field and collect as much current as possible and to improve speed.**

